

Features

- Trench MOSFET Technology
- Excellent Stability And Uniformity
- Moisture Sensitivity Level 3
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

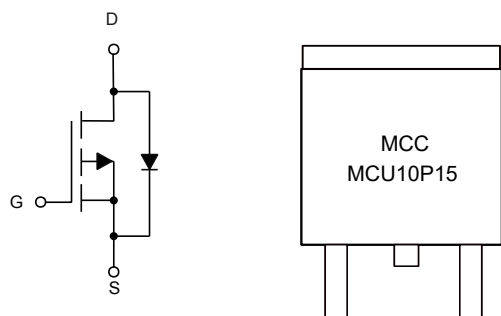
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 50°C/W Junction to Ambient^(Note2)
- Thermal Resistance: 1.8°C/W Junction to Case

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DS}	-150	V	
Gate-Source Voltage	V_{GS}	±20	V	
Continuous Drain Current	I_D	$T_C=25^\circ C$	-10	A
		$T_C=100^\circ C$	-6.3	
Pulsed Drain Current ^(Note3)	I_{DM}	-40	A	
Total Power Dissipation ^(Note4)	P_D	69	W	
Single Pulsed Avalanche Energy ^(Note5)	E_{AS}	36	mJ	

Note:

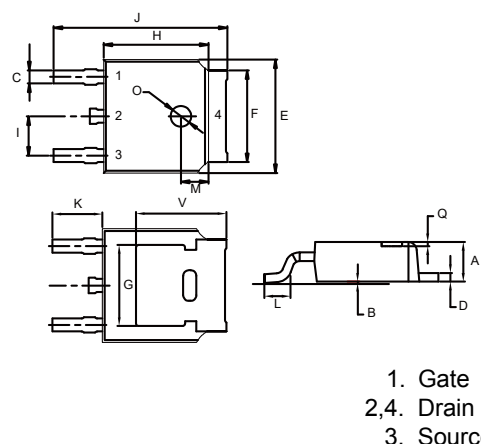
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_d is based on max. junction temperature, using junction-case thermal resistance.
5. $V_{DD}=-50V$, $V_{GS}=-10V$, $R_G=25\Omega$, $L=0.5mH$.

Internal Structure and Marking Code



P-Channel MOSFET

DPAK(TO-252)



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.087	0.094	2.20	2.40	
B	0.000	0.005	0.00	0.13	
C	0.026	0.034	0.66	0.86	
D	0.018	0.023	0.46	0.58	
E	0.256	0.264	6.50	6.70	
F	0.201	0.215	5.10	5.46	
G	0.190		4.83		TYP.
H	0.236	0.244	6.00	6.20	
I	0.086	0.094	2.18	2.39	
J	0.386	0.409	9.80	10.40	
K	0.114		2.90		TYP.
L	0.055	0.067	1.40	1.70	
M	0.063		1.60		TYP.
O	0.043	0.051	1.10	1.30	
Q	0.000	0.012	0.00	0.30	
V	0.211		5.35		TYP.

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-150			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-150V, V_{GS}=0V$			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-2.2	-3.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-2A$		270	310	m Ω
Gate Resistance	R_g	f=1MHz		6		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				-10	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-2A$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_S=-1A, di_f/dt=100A/\mu s$		31		ns
Reverse Recovery Charge	Q_{rr}			46		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-100V, V_{GS}=0V, f=1MHz$		926		pF
Output Capacitance	C_{oss}			40		
Reverse Transfer Capacitance	C_{rss}			24		
Total Gate Charge	Q_g	$V_{DS}=-75V, V_{GS}=-10V, I_D=-1A$		18.9		nC
Gate-Source Charge	Q_{gs}			3.1		
Gate-Drain Charge	Q_{gd}			4.6		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=-75V, V_{GEN}=-10V, R_G=3\Omega, I_{DS}=-1A$		9.1		ns
Turn-On Rise Time	t_r			5.6		
Turn-Off Delay Time	$t_{d(off)}$			36.5		
Turn-Off Fall Time	t_f			70.5		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

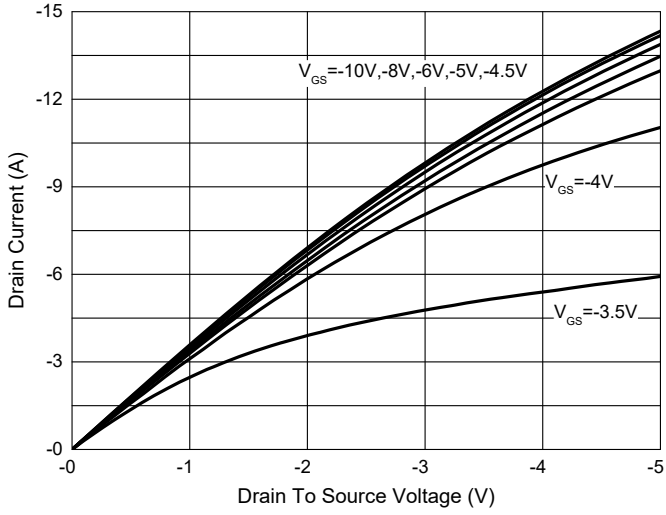


Fig. 2 - Transfer Characteristics

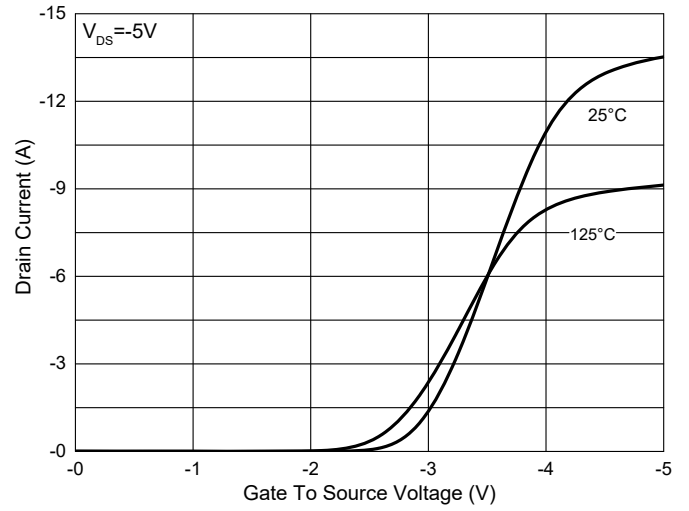


Fig. 3 - $R_{DS(ON)}$ - V_{GS}

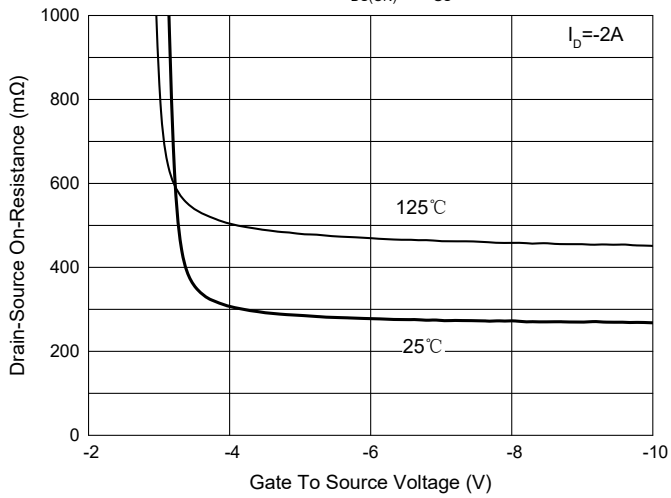


Fig. 4 - $R_{DS(ON)}$ - I_D

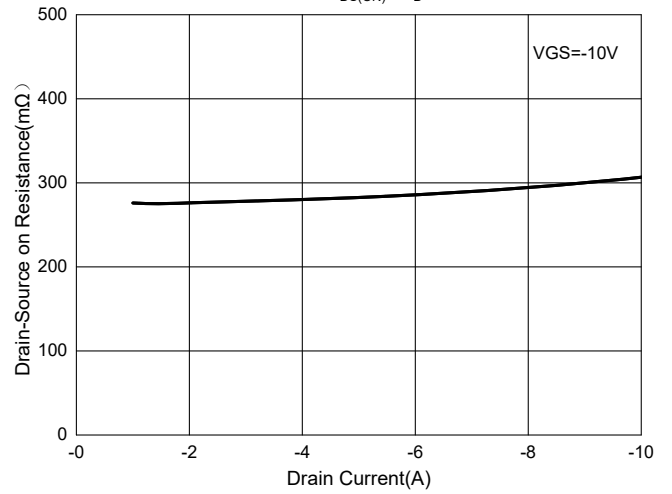


Fig. 5 - Capacitance Characteristics

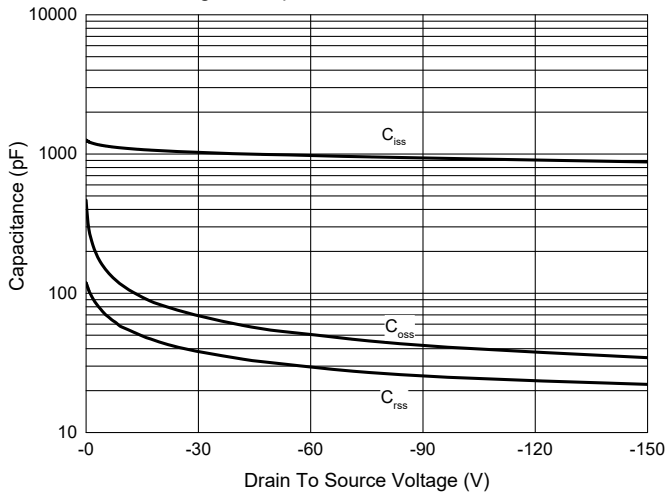
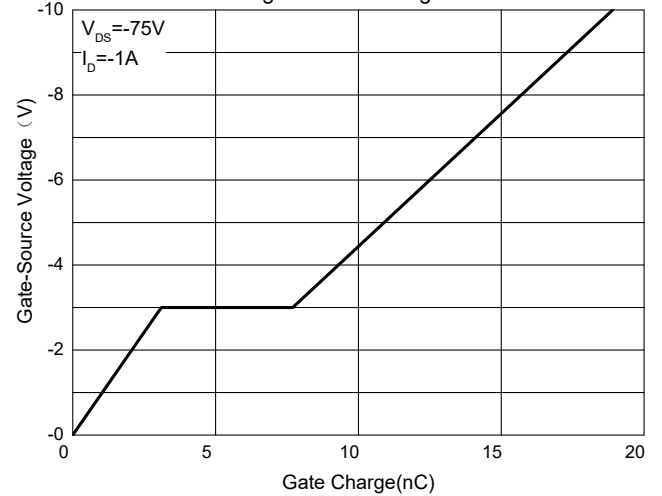


Fig. 6 - Gate Charge



Curve Characteristics

Fig. 7 - Normalized Threshold Voltage

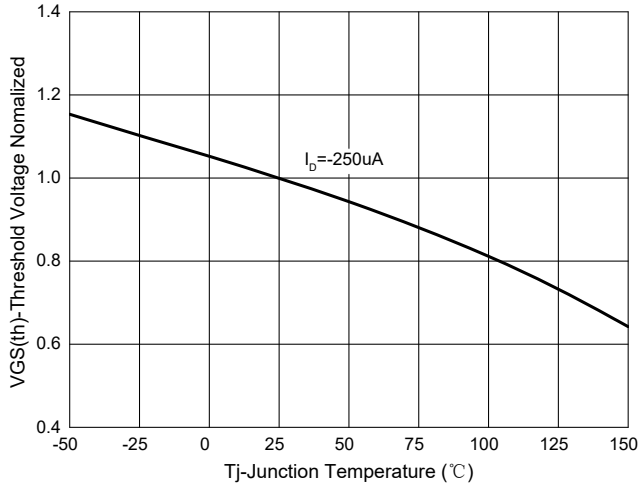


Fig.8-Normalized On Resistance Characteristics

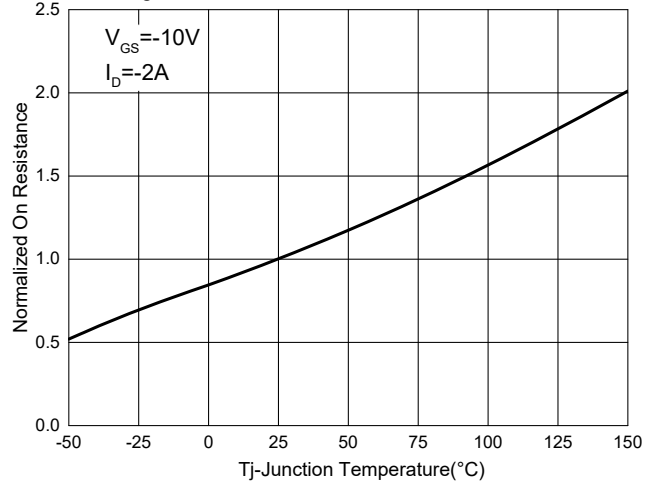


Fig.9 - $I_s - V_{SD}$

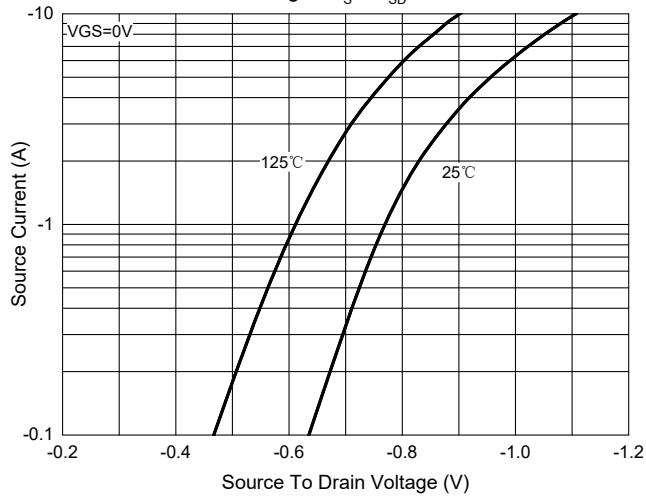


Fig. 10 - Drain Current

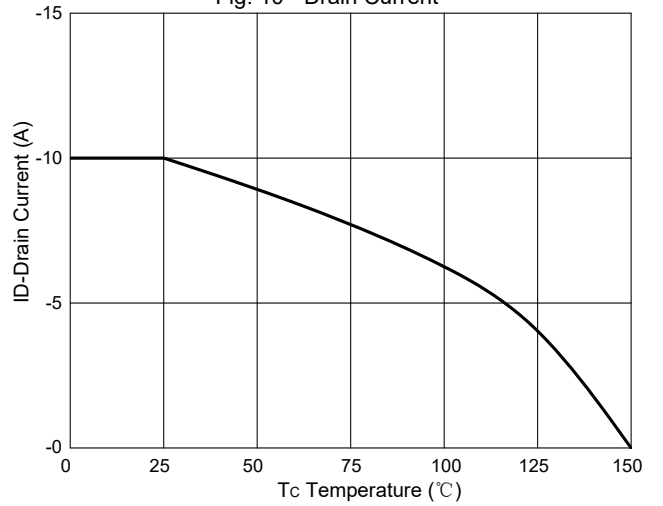
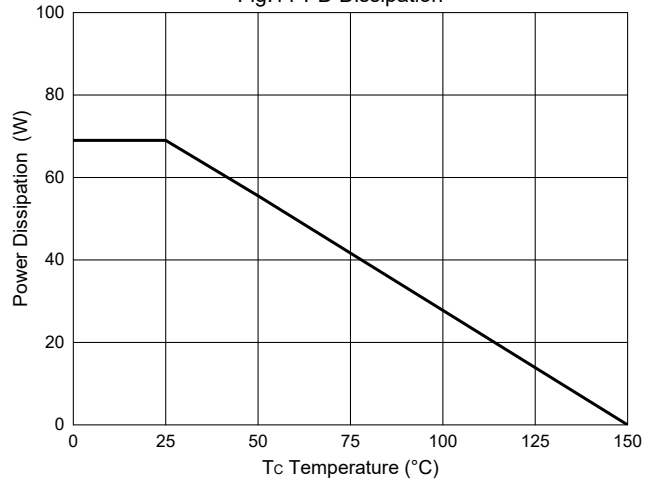


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

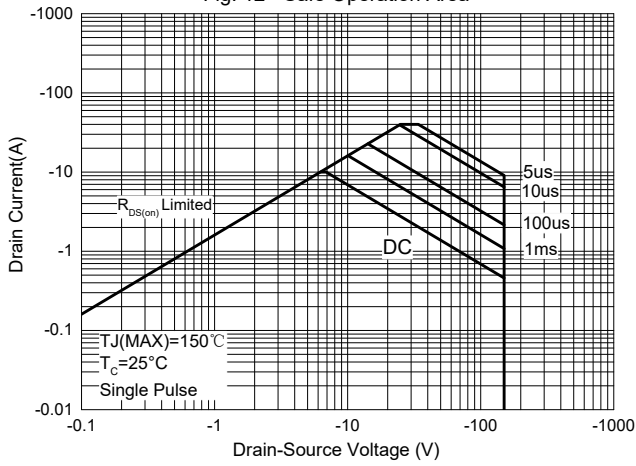
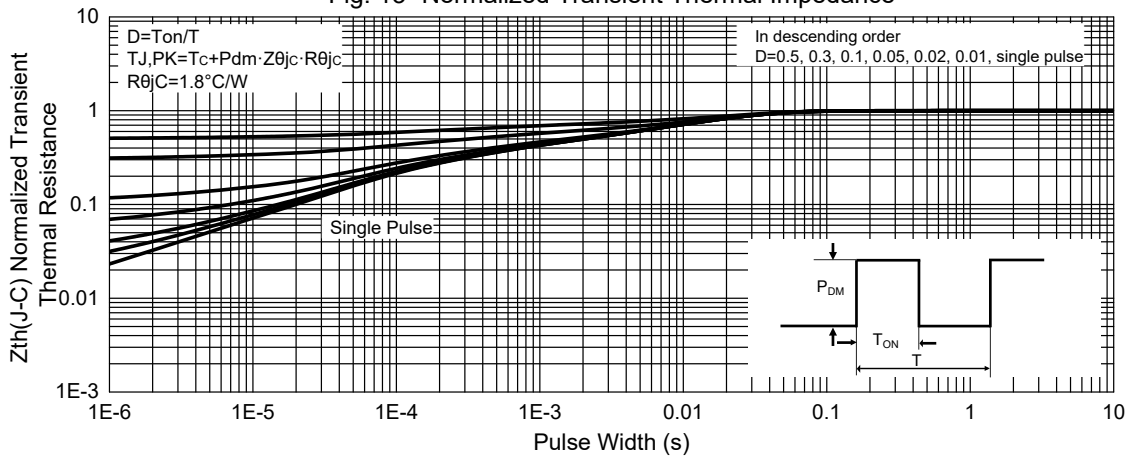


Fig. 13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 2.5Kpcs/Reel

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